ABSTRACT

Disclosed is a film for forming a semiconductor protection film, which protects a surface of a semiconductor element that is mounted on a structure such as a substrate and is located on the outermost side, the surface being on the reverse side of the surface at which the semiconductor element is mounted on the structure, and the resin composition constituting the film for forming a semiconductor protection film contains (A) a thermosetting component and (B) an inorganic filler.